

### IN THE CLAIMS

1. (Previously Presented) A heater device, comprising:  
a heater defining a substantially horizontal planar upper heating surface; and  
a ceramic plate having a substantially horizontal planar lower surface conforming to and supported by said heating surface but not fastened thereto, the ceramic plate substantially entirely covering said upper heating surface, said ceramic plate including an upper supporting surface for supporting an object to be heated by heat conduction through said ceramic plate from said heater to such an object,  
whereby said ceramic plate can be easily placed on and removed from said upper heating surface of said heater, wherein said ceramic plate is solid and devoid of openings for passing fluid therethrough.
2. (Original) A heater device according to claim 1, wherein said heater consists of a ceramic heater.
3. (Original) A heater device according to claim 2, wherein an electrode for radio frequency power is buried in said ceramic heater.
4. (Original) A heater device according to claim 3, wherein said ceramic plate has a thickness of no more than 2 mm.
5. (Original) A heater device according to claim 1, wherein an electrode for radio frequency power is buried in said ceramic plate.
6. (Original) A heater device according to claim 5, wherein said ceramic plate has a thickness of no more than 5 mm.

7. (Previously Presented) A heater device according to claim 1, wherein said ceramic plate is substantially made of ceramic material.

8. (Previously Presented) A heater device according to claim 1, wherein said ceramic plate further comprises an annular low wall surrounding said upper supporting surface.

9. (Previously Presented) A film forming device, comprising:  
a process vessel defining a process chamber;  
a heater defining a heating surface, said heater being placed in said process chamber;  
and  
a ceramic plate simply detachably placed on said heating surface of said heater without being fastened thereto so as to substantially entirely cover said heating surface and defining a supporting surface for supporting an object of a film forming process, wherein said ceramic plate is solid and devoid of openings for passing fluid there through.

10. (Previously Presented) A heater device according to claim 7, wherein said ceramic material consists essentially of aluminum nitride, magnesia, or alumina.

11. (Previously Presented) A film forming device according to claim 9, wherein said heater consists of a ceramic heater.

12. (Previously Presented) A film forming device according to claim 9, wherein an electrode for radio frequency power is buried in said ceramic heater.

13. (Previously Presented) A film forming device according to claim 9, wherein said ceramic plate has a thickness of no more than 2 mm.

14. (Previously Presented) A film forming device according to claim 9, wherein an electrode for radio frequency power is buried in said ceramic plate.

15. (Previously Presented) A film forming device according to claim 9, wherein said ceramic plate has a thickness of no more than 5 mm.

16. (Previously Presented) A film forming device according to claim 9, wherein said ceramic plate is substantially made of ceramic material.

17. (Previously Presented) A film forming device according to claim 9, wherein said ceramic plate further comprises an annular low wall surrounding said supporting surface.

18. (Currently amended) A film forming device according to claim 4 ~~16~~, wherein said ceramic material consists essentially of aluminum nitride, magnesia, or alumina.

19. (Previously Presented) A film forming device according to claim 9, wherein a pressure in the process vessel is controlled in a range of 0.5 torr to 10 torr.

20. (Previously Presented) A film forming device, comprising;  
a process vessel defining a process chamber;  
a heater defining a heating surface, said heater being placed in said process chamber;  
and  
a ceramic plate detachably placed on said heating surface of said heater without being fastened thereto so as to substantially entirely cover said heating surface and defining a supporting surface for supporting an object of a film forming process, wherein said ceramic plate is substantially made of ceramic material.

21. (Cancelled)

22. (New) A heater device, comprising:  
a heater defining a substantially horizontal planar upper heating surface; and  
a ceramic plate having a substantially horizontal planar lower surface conforming to and supported by said heating surface but not fastened thereto, the ceramic plate substantially entirely covering said upper heating surface, said ceramic plate including an upper supporting surface for supporting an object to be heated by heat conduction through said ceramic plate from said heater to such an object,  
whereby said ceramic plate can be easily placed on and removed from said upper heating surface of said heater,  
wherein said ceramic plate is substantially made of ceramic material.

23. (New) The heater device of claim 22, wherein said ceramic plate is directly placed on said upper heating surface.

24. (New) The heater device of claim 1, wherein said ceramic plate is substantially made of a ceramic material and has a thickness sufficient to be handled individually.

25. (New) The heater device of claim 1, wherein the thickness ranges from 1 mm to 5 mm.

26. (New) A method of using a heater device according to claim 1, comprising:

providing the heater defining a substantially horizontal planar upper heating surface; and

placing the ceramic plate on the upper heating surface;

placing a wafer on the ceramic plate;

heating the wafer;

removing the wafer from the ceramic plate; and

removing the ceramic plate from the heater.